



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3B0365J		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA000981080						
<b>Package</b>		PG-DIP-8-13		<b>Weight*</b>		556.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.248	0.40	0.40	4037	4037
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7716	
wire	non noble metal	copper	7440-50-8	174.475	31.33	32.15	313296	321494
	noble metal	gold	7440-57-5	0.269	0.05	0.05	483	483
	encapsulation	organic material	carbon black	1333-86-4	1.097	0.20		1969
encapsulation	plastics	epoxy resin	-	35.464	6.37		63680	
	inorganic material	silicondioxide	60676-86-0	329.045	59.08	65.65	590850	656499
leadfinish	non noble metal	tin	7440-31-5	7.496	1.35	1.35	13460	13460
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1429	1429
glue	plastics	epoxy resin	-	0.217	0.04		390	
	noble metal	silver	7440-22-4	1.230	0.22	0.26	2208	2598
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com